

Abstract

An object is to provide an interposer that has independence for repairability and further makes it possible to prevent electrical connection failures which may be caused by an assembly position misalignment of a semiconductor device. An interposer is provided with: an inner layer structure including at least one inner layer wiring layer; a first outer layer structure provided on a first surface of the inner layer structure; and a second outer layer structure provided on a second surface of the inner layer structure. Further, the inner layer wiring layer includes a first insulating resin layer, a wiring provided on a surface of the first insulating resin layer, and a via being connected to the wiring and penetrating the first insulating resin layer. The first outer layer structure and the second outer layer structure each include a second insulating resin layer and an external connection via penetrating the second insulating resin layer. The second insulating resin layer has an external connection opening part so as to make it possible for an external connection electrode of the semiconductor device to fit into a surface of one of the first outer layer structure and the second outer layer structure.